

METHOD FOR BOTTOMLESS DEPOSITION OF BARRIER LAYERS
IN INTEGRATED CIRCUIT METALLIZATION SCHEMES

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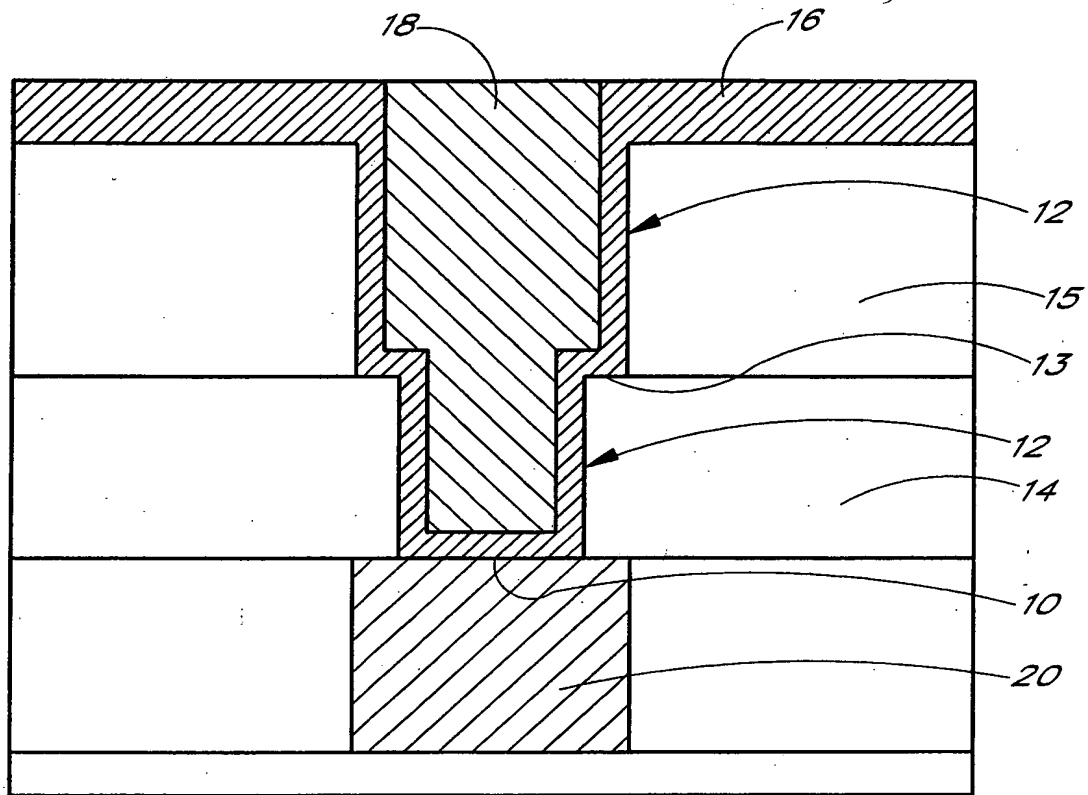


FIG. 1
(PRIOR ART)

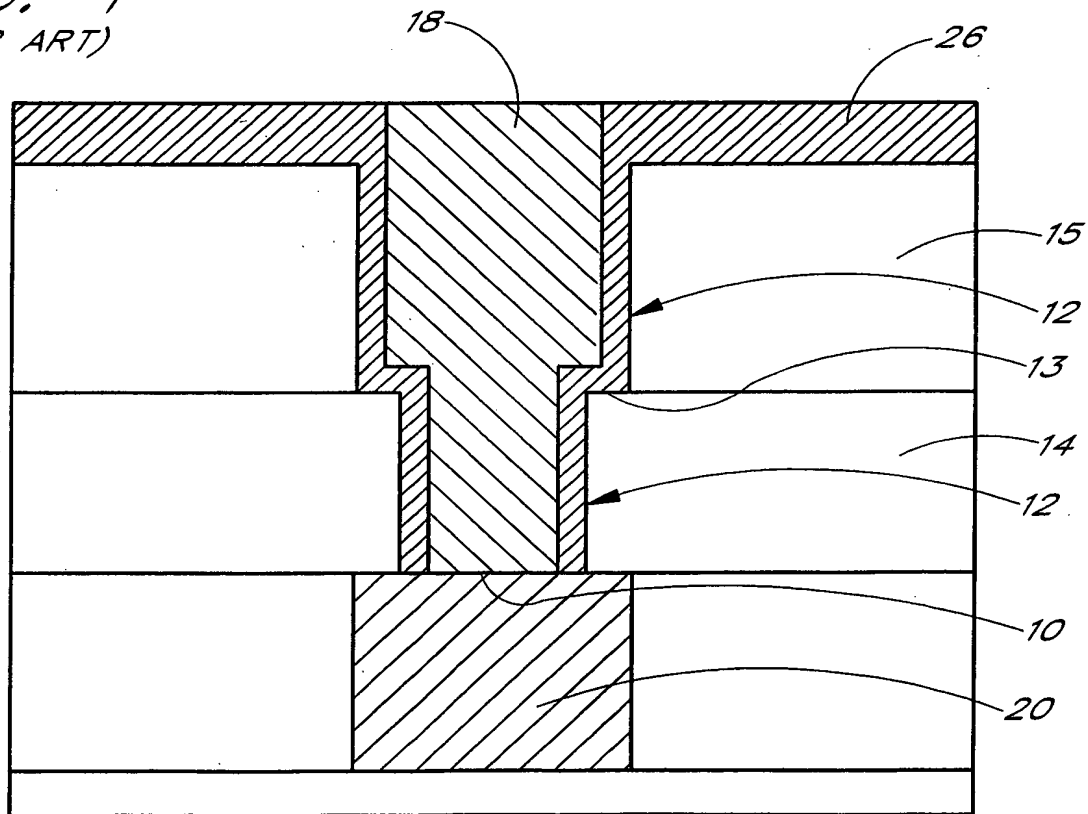


FIG. 2